

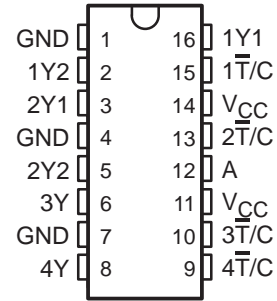
CDC329A

1-LINE TO 6-LINE CLOCK DRIVER WITH SELECTABLE POLARITY

SCAS328B – DECEMBER 1992 – REVISED OCTOBER 1998

- Low Output Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and CMOS-Compatible Outputs
- Distributes One Clock Input to Six Clock Outputs
- Polarity Control Selects True or Complementary Outputs
- Distributed V_{CC} and GND Pins Reduce Switching Noise
- High-Drive Outputs (–32-mA I_{OH}, 32-mA I_{OL})
- State-of-the-Art EPIC-II B™ BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (D)

**D PACKAGE
(TOP VIEW)**



description

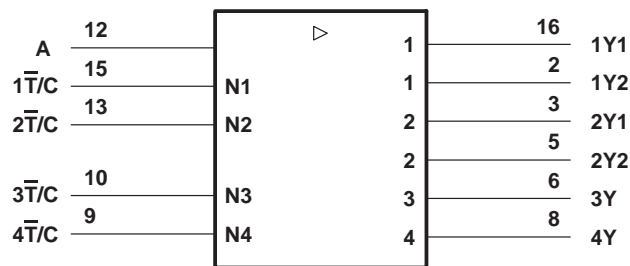
The CDC329A contains a clock-driver circuit that distributes one input signal to six outputs with minimum skew for clock distribution. Through the use of the polarity-control inputs (\bar{T}/C), various combinations of true and complementary outputs can be obtained.

The CDC329A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

| INPUTS | | OUTPUT |
|-------------|---|--------|
| \bar{T}/C | A | Y |
| L | L | L |
| L | H | H |
| H | L | H |
| H | H | L |

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-II B is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

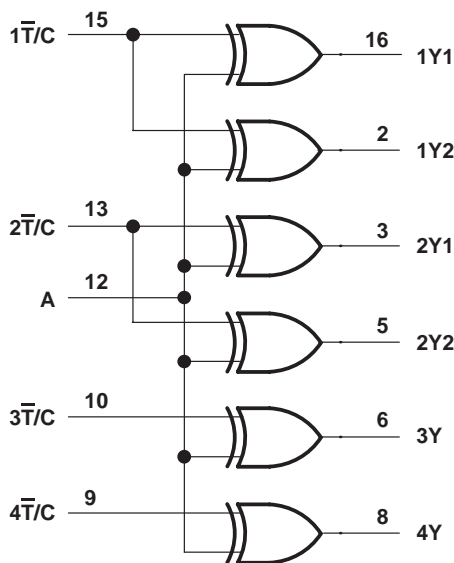
**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1998, Texas Instruments Incorporated

CDC329A
1-LINE TO 6-LINE CLOCK DRIVER
WITH SELECTABLE POLARITY
 SCAS328B – DECEMBER 1992 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|--|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to 7 V |
| Voltage range applied to any output in the high state or power-off state, V_O (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V |
| Current into any output in the low state, I_O | 64 mA |
| Input clamp current, I_{IK} ($V_I < 0$) | -18 mA |
| Output clamp current, I_{OK} ($V_O < 0$) | -50 mA |
| Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2) | 0.77 W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



recommended operating conditions (see Note 3)

| | | MIN | NOM | MAX | UNIT |
|---------------------|------------------------------------|------|-----|----------|------|
| V_{CC} | Supply voltage | 4.75 | 5 | 5.25 | V |
| V_{IH} | High-level input voltage | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 0.8 | V |
| V_I | Input voltage | 0 | | V_{CC} | V |
| I_{OH} | High-level output current | | | -32 | mA |
| I_{OL} | Low-level output current | | | 32 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | | 5 | ns/V |
| f_{clock} | Input clock frequency | | | 80 | MHz |
| T_A | Operating free-air temperature | -40 | | 85 | °C |

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

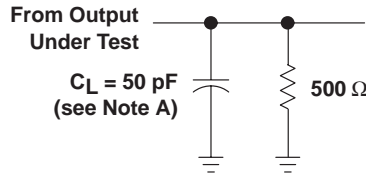
| PARAMETER | TEST CONDITIONS | | MIN | TYP† | MAX | UNIT |
|-----------|--|--------------------------|-------------|--------------|---------|---------------|
| V_{IK} | $V_{CC} = 4.75\text{ V}$, | $I_I = -18\text{ mA}$ | | | -1.2 | V |
| V_{OH} | $V_{CC} = 4.75\text{ V}$, | $I_{OH} = -32\text{ mA}$ | 3.85 | | | V |
| V_{OL} | $V_{CC} = 4.75\text{ V}$, | $I_{OL} = 32\text{ mA}$ | | | 0.55 | V |
| I_I | $V_{CC} = 5.25\text{ V}$, | $V_I = V_{CC}$ or GND | | | ± 1 | μA |
| I_{CC} | $V_{CC} = 5.25\text{ V}$, | $V_I = V_{CC}$ or GND, | $I_O = 0$, | Outputs high | 10 | mA |
| | | | | Outputs low | 40 | |
| C_i | $V_I = 2.5\text{ V}$ or 0.5 V | | | 3 | | pF |

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

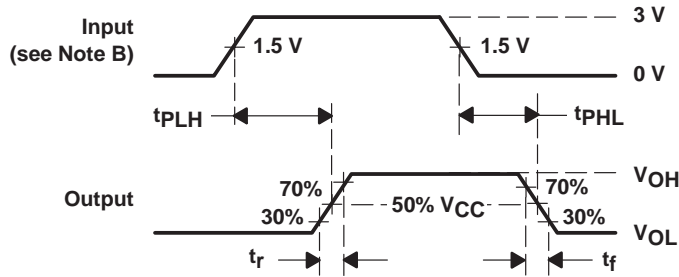
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figures 1 and 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | MIN | TYP | MAX | UNIT |
|-------------|--------------|--------------------|-----|------|-----|------|
| t_{PLH} | A | Any Y | 2 | | 5.9 | ns |
| t_{PHL} | | | 1.7 | | 5.9 | |
| t_{PLH} | \bar{T}/C | Any Y | 1.5 | | 5 | ns |
| t_{PHL} | | | 1.5 | | 5 | |
| $t_{sk(o)}$ | A | Any Y (same phase) | | | 0.6 | ns |
| | | Any Y (any phase) | | | 1.5 | |
| t_r | | | | 1.3 | | ns |
| t_f | | | | 0.85 | | ns |

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR OUTPUTS

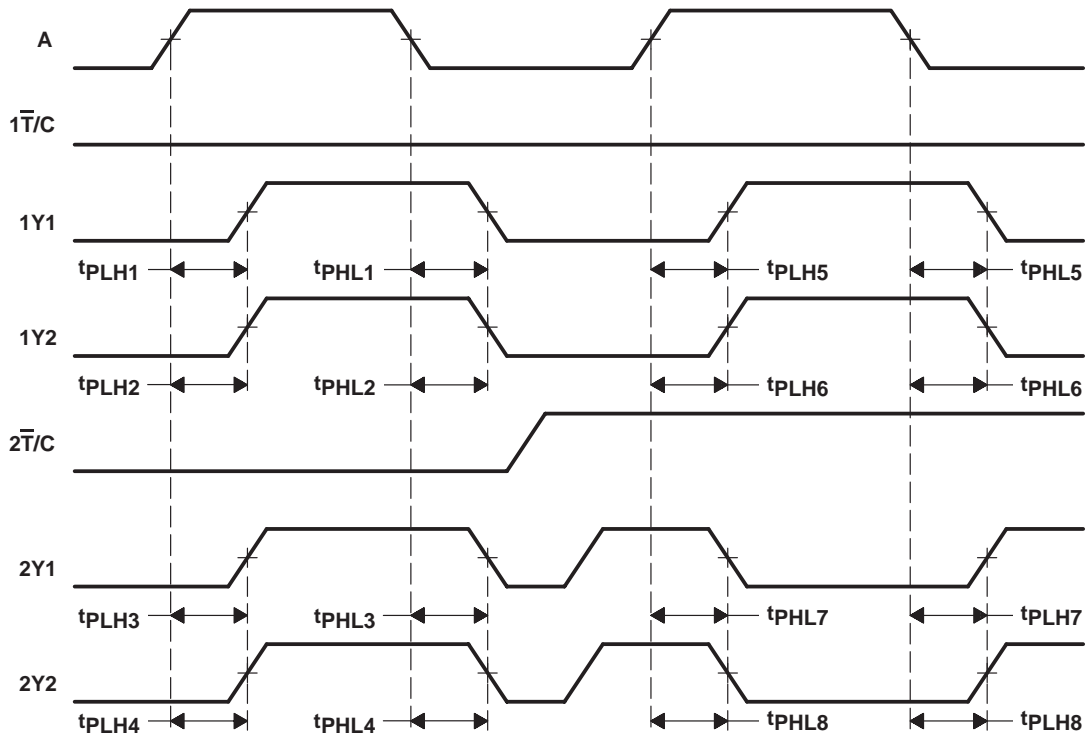


VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew, $t_{sk(o)}$, from A to any Y (same phase), can be measured only between outputs for which the respective polarity-control inputs ($\overline{T/C}$) are at the same logic level. It is calculated as the greater of:
- The difference between the fastest and slowest of t_{PHL} from $A\downarrow$ to any Y (e.g., t_{PHLn} , $n = 1$ to 4; or t_{PHLn} , $n = 5$ to 6)
 - The difference between the fastest and slowest of t_{PHL} from $A\downarrow$ to any Y (e.g., t_{PHLn} , $n = 1$ to 4; or t_{PHLn} , $n = 5$ to 6)
 - The difference between the fastest and slowest of t_{PLH} from $A\downarrow$ to any Y (e.g., t_{PLHn} , $n = 7$ to 8)
 - The difference between the fastest and slowest of t_{PHL} from $A\uparrow$ to any Y (e.g., t_{PHLn} , $n = 7$ to 8)
- B. Output skew, $t_{sk(o)}$, from A to any Y (any phase), can be measured between outputs for which the respective polarity-control inputs ($\overline{T/C}$) are at the same or different logic levels. It is calculated as the greater of:
- The difference between the fastest and slowest of t_{PLH} from $A\uparrow$ to any Y or t_{PHL} from $A\uparrow$ to any Y (e.g., t_{PLHn} , $n = 1$ to 4; or t_{PLHn} , $n = 5$ to 6, and t_{PHLn} , $n = 7$ to 8)
 - The difference between the fastest and slowest of t_{PHL} from $A\downarrow$ to any Y or t_{PLH} from $A\downarrow$ to any Y (e.g., t_{PHLn} , $n = 1$ to 4; or t_{PHLn} , $n = 5$ to 6, and t_{PLHn} , $n = 7$ to 8)

Figure 2. Waveforms for Calculation of $t_{sk(o)}$

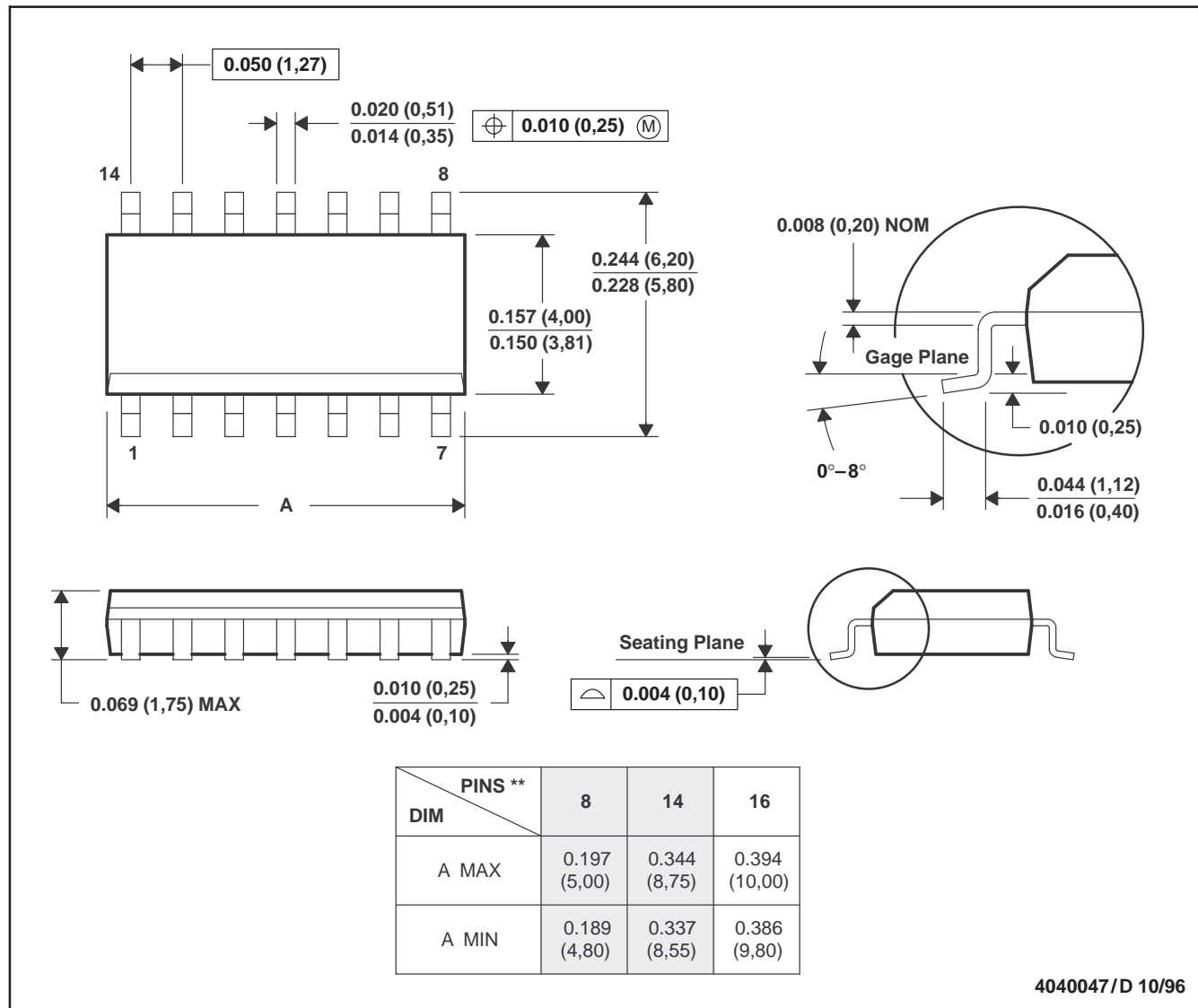
CDC329A
1-LINE TO 6-LINE CLOCK DRIVER
WITH SELECTABLE POLARITY
 SCAS328B – DECEMBER 1992 – REVISED OCTOBER 1998

MECHANICAL INFORMATION

D (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CDC329AD | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CDC329ADBLE | OBSOLETE | SSOP | DB | 16 | | TBD | Call TI | Call TI |
| CDC329ADG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CDC329ADR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CDC329ADRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

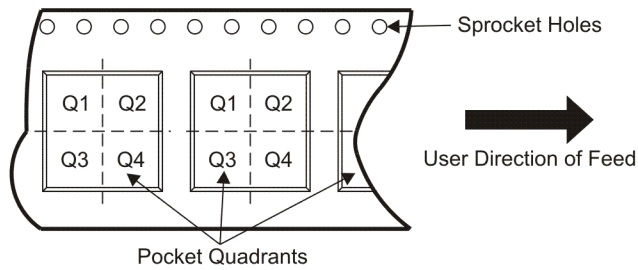
Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CDC329ADR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------|--------------|-----------------|------|------|-------------|------------|-------------|
| CDC329ADR | SOIC | D | 16 | 2500 | 346.0 | 346.0 | 33.0 |

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

| | |
|-----------------------------|--|
| Amplifiers | amplifier.ti.com |
| Data Converters | dataconverter.ti.com |
| DSP | dsp.ti.com |
| Clocks and Timers | www.ti.com/clocks |
| Interface | interface.ti.com |
| Logic | logic.ti.com |
| Power Mgmt | power.ti.com |
| Microcontrollers | microcontroller.ti.com |
| RFID | www.ti-rfid.com |
| RF/IF and ZigBee® Solutions | www.ti.com/lprf |

Applications

| | |
|--------------------|--|
| Audio | www.ti.com/audio |
| Automotive | www.ti.com/automotive |
| Broadband | www.ti.com/broadband |
| Digital Control | www.ti.com/digitalcontrol |
| Medical | www.ti.com/medical |
| Military | www.ti.com/military |
| Optical Networking | www.ti.com/opticalnetwork |
| Security | www.ti.com/security |
| Telephony | www.ti.com/telephony |
| Video & Imaging | www.ti.com/video |
| Wireless | www.ti.com/wireless |

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View CDC329ADR](#) on WIN SOURCE

 [Texas Instruments](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management